

L Number	Hits	Search Text	DB	Time stamp
13	39	(US-6225206-\$ or US-5143865-\$ or US-5824438-\$ or US-6162660-\$ or US-6294828-\$ or US-6130476-\$ or US-6251766-\$ or US-6337522-\$ or US-3839727-\$ or US-6260264-\$ or US-5956605-\$ or US-6425516-\$ or US-6118179-\$ or US-6168972-\$ or US-6180504-\$ or US-6291270-\$ or US-5989982-\$ or US-5656863-\$ or US-5897337-\$ or US-6410415-\$ or US-6189208-\$ or US-5747101-\$ or US-5329423-\$ or US-4818728-\$ or US-6100114-\$ or US-5704116-\$).did. or (US-5650667-\$ or US-6355507-\$ or US-5933713-\$ or US-5869899-\$ or US-5496775-\$ or US-6288335-\$ or US-5908317-\$ or US-6054772-\$ or US-5824569-\$ or US-6380061-\$ or US-6281591-\$ or US-5554887-\$ or US-5641113-\$).did.	USPAT	2002/12/28 10:35
14	5748	(flipchip (flip adj chip)) and (solder adj (bump ball))	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/12/28 10:40
15	8874	{substrate ((wiring circuit) adj board)) near3 polyimide	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/12/28 10:44
16	384	((flipchip (flip adj chip)) and (solder adj (bump ball))) and ((substrate ((wiring circuit) adj board)) near3 polyimide)	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/12/28 10:43
17	377	((flipchip (flip adj chip)) and (solder adj (bump ball))) and ((substrate ((wiring circuit) adj board)) near3 polyimide)) not ((US-6225206-\$ or US-5143865-\$ or US-5824438-\$ or US-6162660-\$ or US-6294828-\$ or US-6130476-\$ or US-6251766-\$ or US-6337522-\$ or US-3839727-\$ or US-6260264-\$ or US-5956605-\$ or US-6425516-\$ or US-6118179-\$ or US-6168972-\$ or US-6180504-\$ or US-6291270-\$ or US-5989982-\$ or US-5656863-\$ or US-5897337-\$ or US-6410415-\$ or US-6189208-\$ or US-5747101-\$ or US-5329423-\$ or US-4818728-\$ or US-6100114-\$ or US-5704116-\$).did. or (US-5650667-\$ or US-6355507-\$ or US-5933713-\$ or US-5869899-\$ or US-5496775-\$ or US-6288335-\$ or US-5908317-\$ or US-6054772-\$ or US-5824569-\$ or US-6380061-\$ or US-6281591-\$ or US-5554887-\$ or US-5641113-\$).did.)	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/12/28 10:43
18	9469	(cap cover lid) near3 (polyimide polymer polymeric)	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/12/28 10:44
19	44445	{substrate ((wiring circuit) adj board)) near3 (polyimide polymer polymeric)	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/12/28 12:08
20	696	((flipchip (flip adj chip)) and (solder adj (bump ball))) and ((substrate ((wiring circuit) adj board)) near3 (polyimide polymer polymeric))	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/12/28 10:59

21	21	((cap cover lid) near3 (polyimide polymer polymeric)) and (((flipchip (flip adj chip)) and (solder adj (bump ball))) and ((substrate ((wiring circuit) adj board)) near3 (polyimide polymer polymeric)))	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/12/28 12:06
22	2	"6392143"	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/12/28 12:06
23	115	"5285352"	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/12/28 12:06
24	8	"6093972"	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/12/28 12:06
25	28	"5724729"	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/12/28 12:07
26	93	"5067007"	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/12/28 12:07
27	9	"5982038"	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/12/28 12:07
28	72	"5311402"	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/12/28 12:07
29	315	"6392143" "5285352" "6093972" "5724729" "5067007" "5982038" "5311402"	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/12/28 12:07
30	315	("6392143" "5285352" "6093972" "5724729" "5067007" "5982038" "5311402") not ((US-6225206-\$ or US-5143865-\$ or US-5824438-\$ or US-6162660-\$ or US-6294828-\$ or US-6130476-\$ or US-6251766-\$ or US-6337522-\$ or US-3839727-\$ or US-6260264-\$ or US-5956605-\$ or US-6425516-\$ or US-6118179-\$ or US-6168972-\$ or US-6180504-\$ or US-6291270-\$ or US-5989982-\$ or US-5656863-\$ or US-5897337-\$ or US-6410415-\$ or US-6189208-\$ or US-5747101-\$ or US-5329423-\$ or US-4818728-\$ or US-6100114-\$ or US-5704116-\$).did. or (US-5650667-\$ or US-6355507-\$ or US-5933713-\$ or US-5869899-\$ or US-5496775-\$ or US-6288335-\$ or US-5908317-\$ or US-6054772-\$ or US-5824569-\$ or US-6380061-\$ or US-6281591-\$ or US-5554887-\$ or US-5641113-\$).did.) not (((cap cover lid) near3 (polyimide polymer polymeric)) and (((flipchip (flip adj chip)) and (solder adj (bump ball))) and ((substrate ((wiring circuit) adj board)) near3 (polyimide polymer polymeric))))	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/12/28 12:08
31	27	("6392143" "5285352" "6093972" "5724729" "5067007" "5982038" "5311402") and (substrate ((wiring circuit) adj board)) near3 (polyimide polymer polymeric)	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/12/28 12:47
32	6	6093972.URPN.	USPAT	2002/12/28 12:19

33	8	{"5089440"   "5218759"   "5285352"   "5302849"   "5371404"   "5659203"   "5864178"   "5900581").PN.	USPAT	2002/12/28 12:24
36	15	"6025648"	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/12/28 12:43
37	10	"6239496"	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/12/28 12:44
38	11	"6188127"	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/12/28 12:46
40	19	("6025648" "6239496" "6188127") and (polyimide polymer polymeric)	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/12/28 12:47
39	32	"6025648" "6239496" "6188127"	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/12/28 13:01
41	13	("6025648" "6239496" "6188127") not (("6025648" "6239496" "6188127") and (polyimide polymer polymeric))	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/12/28 13:01